Novel Model of OCA in IC and Its Implementation on Hadoop

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Abstract-In the manufacturing process of Integrated Circuit (IC), defects existing in real layout are inevitable. Defects cause circuit fault, which reduces the yield and increases the IC cost. Reducing the Critical Area (CA) can lower the occurrence of circuit fault. In this paper, a novel model of Open Critical Area (OCA) are proposed. Firstly, according to the net matrix and the morphological theory, the edge of nets is extracted. Secondly, the defect replications are operated on all horizontal lines and vertical lines of the edge of nets. Then, we extract the OCA extraction on nets by reducing replication times and increasing the moving distance of defects. Finally, in order to further reduce the extraction time of OCA, the new model is implemented on Hadoop. Compared with the existing model based on the net flow-axis, the experimental results on synthesized OpenSparc circuit and three nodes of the cluster on Hadoop show that the proposed model is more efficient without accuracy loss.

Index Terms—open critical area, defects, Hadoop

I. INTRODUCTION

With the boom in nanoscale IC [1]-[3], it is difficult to acquire the desired yield by making use of the IC design rules when designing layouts [4]-[9]. For the sake of determining the yield loss mainly caused by defects in the manufacturing process [10], [11], experts proposed the definition and extraction algorithm of CA [12]-[18]. CA is the area of a layout at which the occurrence of a defect would result in functional failure. If the area where the occurrence of a defect would result in an open failure, it is called OCA. The yield can be raised successfully by reducing CA of layouts, thereby reducing IC cost [19], [20]. Concern for the accuracy and extraction efficiency of CA is at the core of yield improvement [21].

For the extraction of CA, the model proposed by Wang *et al.* is relatively precise because it is based on the net flow-axis [22]. It can extract CA of different shapes nets with higher precision, but with low efficiency and high time complexity. Contrast to the former, the model proposed by Wang and Wu is more efficient, which lowers the time complexity and reduces the extraction time of short CA [23]. But it does not put forward OCA model and rapid extraction algorithm, which is the key factor restricting the layout optimization and sensitivity calculation. In order to reduce extraction time of OCA

and receive a high precision, this paper proposes a new model of OCA. This model is first applied to the edge of arbitrary nets. In new model, CA extraction of arbitrary nets is optimized. Replication times of defects on arbitrary nets is reduced owing to the reason that the defect centroid is moved a defect's feature size rather than a grid unit when continuing to copy next defect. Moreover, because a defect is copied partially on rectangle nets, the number of points of one replication operation is also decreased. Since implemented on Hadoop, novel model further improves OCA extraction speed.

II. NOVEL MODEL OF OCA

OCA of layouts is caused by defects. In the novel model, the layout and defect can both be converted to a two-dimensional matrix. If the point is covered by nets or defect, the matrix value of this point is 1.

A. Novel Modeling of OCA Based on Defect Characteristics

For a single net N(i, j) with row range and column range, whose OCA can be obtained by expanding the boundary of this net. For a random defect $D(X_C, Y_C)$, suppose the characteristic size of a defect is $D_1 u \times D_2 u$, and the centroid is (X_C, Y_C) . u is the size of a grid on circuit layout. The OCA composed of the centroid of the defect on the net is as shown in formula (1)–(3).

$$A_{O}\left(X_{C}, Y_{C}, N\right) = \sum_{i=1}^{numi} \left(\bigcup_{\substack{i_{H} \in H_{i} \\ j_{H} = y_{i}}} D_{R}\left(i_{H}, j_{H}\right)\right) + \sum_{i=1}^{numj} \left(\bigcup_{i=1}^{numj} D_{R}\left(i_{H}, j_{H}\right)\right)$$
(1)

$$\sum_{j=1} \left(\bigcup_{\substack{i_V = x_j \\ j_V \in V_j}} D_R(i_V, j_V) \right)$$

$$H_{i} = \{x_{min}, x_{min} + D_{1}, x_{min} + 2D_{1}, \dots, x_{max}\}$$
(2)

$$V_{i} = \{y_{min}, y_{min} + D_{2}, y_{min} + 2D_{2}, ..., y_{max}\}$$
(3)

In formula (1), $A_o(X_C, Y_C, N)$ is a two-dimensional matrix, whose size is same as the layout. The area of $A_o(X_C, Y_C, N)$ in which matrix value exceeds 1 is defined as OCA. *numi* is the number of horizontal lines

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in boundary of this net. *numj* is the number of vertical lines in boundary of this net. H_i represents the numerical range of the x-axis direction crossed by the *ith* horizontal line. y_i represents the value of the y-axis direction occupied by the *ith* horizontal line. V_j represents the numerical range of the y-axis direction crossed by the *jth* vertical line. x_j represents the value of the x-axis direction crossed by the *jth* vertical line.

B. Algorithm Steps of Novel Model

In order to improve the feasibility of novel model given in previous section, corresponding algorithm steps are proposed. The layout and defect can be transformed into a two-dimensional matrix. The conversion rule of layout is defined as follows, if the net covers the point (i, j), then the value on this point in matrix equals 1, otherwise 0. The transformation rule of the defect in matrix is similar to the above conversion, if the defect overlap with the point (i, j), then the value on this point in matrix equals 1, natrix is similar to the above conversion, if the defect overlap with the point (i, j), then the value on this point in matrix equals 1, otherwise 0.

Algorithm Steps. Algorithm steps to extract OCA according to novel model

Step 1 Obtain binary image of a layout and save it in a matrix $img_{N1\times N2}$ and create a matrix $result_{N1\times N2}$ whose value of every point are 0.

Step 2 Extract the characteristics and centroid of the defect, and save the defect in a matrix $D_{D_1 \times D_2}$.

Step 3 Split every net in layouts according to connectivity, label a single net n which is a positive number smaller than num, num is the number of nets, and initialize n with integer 1.

Step 4 Extract the boundary of the net. Moreover, obtain horizontal lines and vertical lines in the boundary.

Step 5 Get the numerical range of the x-axis direction $[x_{min}, x_{max}]$ and the value of the y-axis direction y of the horizontal line. Initialize the point (R_m, C_n) of net *n* with (x_{min}, y) .

Step 6 Copy $D(R_m, C_n)$, and append the replication result in corresponding points of $re sult_{N1 \times N2}$. If $R_m < x_{max}$, then $R_m = R_m + D_1$ and return to Step 6, otherwise jump to Step 7.

Step 7 If all horizontal lines have been processed, return to Step 5, otherwise jump to Step 8.

Step 8 Get the numerical range of the y-axis direction $[y_{min}, y_{max}]$ and the value of the x-axis direction x of the vertical line. Initialize the point (R_m, C_n) of net n with (x, y_{min}) .

Step 9 Copy $D(R_m, C_n)$, and append the replication result in corresponding points of $re sult_{N1 \times N2}$. If $C_n < y_{max}$, then $C_n = C_n + D_2$ and return to Step 9, otherwise jump to Step 10. Step 10 If all vertical lines have been processed, return to Step 8, otherwise jump to Step 11.

Step 11 Let n=n+1, if $n \le num$, return to Step 4, otherwise jump to Step 12.

Step 12 Compute the area of the domain where the matrix value exceeds 1 in $re sult_{N1 \times N2}$.

The explanation of the algorithm above is shown as follows. Steps 1–3 can determine layout matrix, defect matrix and the number of nets. Step 4 obtains horizontal lines and vertical lines in the boundary of nets. Defect replication of each horizontal line is realized in Step 5-7.Similarly, defect replication of each vertical line is realized in Step 8-11. The step 12 completes the extraction operation for all nets. The step 14 calculates the value of OCA.

C. Performance Analysis of Novel Model

In this paper, we analyze mainly the time complexity of the novel model. The executive time of the model on a net of r_n rows and c_n columns mainly depends on the defect copy operation of certain options. Because this model is realized in the boundary of a net and the defect centroid is moved a defect's feature size rather than a grid

unit, so times of copy operation on a net are $2\left(\frac{r_n}{D_1}+1\right)$

or
$$2\left(\frac{c_n}{D_2}+1\right)$$
. $2\left(\frac{r_n}{D_1}+1\right)$ is times of copy operation on

the horizontal net, and $2\left(\frac{c_n}{D_2}+1\right)$ is times of copy

operation on the horizontal net. Furthermore, the number of points of a copy operation on a single net is $D_1 \times D_2$. Let constant C be the time of one assignment operation, so the time of replication operation on a net is

$$C\left(\frac{2r_n}{D_1}+2\right) \times D_1 \times D_2 \text{ or } C\left(\frac{2c_n}{D_2}+2\right) \times D_1 \times D_2.$$

In order to understand better the advantage of new model in the time complexity, we analyze each net of a layout named SRAM in Fig. 1. Aimed to a single net labeled integer from 1 to 13, for the net 1, its components-vertical and horizontal lines are extracted in Fig. 2. Moreover, times of the defect copied is analyzed in Fig. 3. In the graph above, compared with the two model from Reference [11] and Reference [22] severally, the new model proposed in this paper is superior to them whether times of the defect copied.



Figure 1. SRAM layout.



(a). Vertical lines.(b). Horizontal lines.Figure 2. Components the net 1-vertical and horizontal lines.



Figure 3. Times of the defect copied on each net.

III. IMPLEMENTATION OF NOVEL MODEL

To verify suitability of the new model, every layout layer of 43-active from synthesized OpenSparc circuit is tested under different defect sizes. There are the 7 group layouts in these layout layers, and each group has different number of nets. *Nets* represents the number of nets on the layout layer. The feature size of the defect is taken as $18u \times 18u$, $20u \times 20u$ and $25u \times 25u$ respectively. The u^2 is the unit of the OCA, and u is the size of a grid on circuit layout. The unit of time is s (second).

A. Implementation of New Algorithm

The proposed model in this paper and the existing model in [22] are implemented on the same computer. Hardware configurations of the computer are: Intel(R) Pentium (R) CPU G 645 @ 2.90 GHz and 4 GB's memory physical address extension. Experiment results is shown as Table I, Table II and Table III. Among which, the column A_o represents the OCA applying the existing model in Reference [22], and A_N represents the OCA applying the proposed model in this paper. Similarly, T_o and T_N represent the extraction time applying the existing model in Reference [22] and the proposed model in this paper respectively.

From Table I, Table II and Table III, A_N is equal to A_o . However, T_N is obviously less than T_o . It is proved that the proposed model in this paper significantly improves the extraction efficiency of OCA under the condition of guaranteed accuracy. This characteristic is advantageous to the development of IC.

TABLE I. THE SIZE OF DEFECT IS 18u×18u

Layout	Nets	$A_o(10^6)/{\rm u}^2$	$A_{N}(10^{6})/u^{2}$	$T_o(10^4)/{\rm s}$	$T_N(10^4)/{ m s}$
1	6577	4.404	4.404	0.920	0.239
2	4990	4.595	4.595	0.746	0.160
3	3696	1.342	1.342	0.401	0.093
4	30,824	31.563	31.563	5.157	0.829
5	23,505	23.297	23.297	3.755	0.611
6	6216	6.951	6.951	0.868	0.189
7	12,816	9.538	9.538	1.818	0.376

TABLE II.	THE SIZE OF DEFECT IS	$20\mu \times 20\mu$
	THE BILLE OF BEILDET ID	2000 2000

Layout	Nets	$A_o(10^6)/u^2$	$A_N(10^6)/u^2$	$T_o(10^4)/s$	$T_N(10^4)/{ m s}$
1	6577	11.549	11.549	0.925	0.259
2	4990	7.716	7.716	0.850	0.169
3	3696	2.243	2.243	0.464	0.097
4	30,824	65.831	65.831	5.328	1.249
5	23,505	38.385	38.385	3.830	0.917
6	6216	11.153	11.153	0.906	0.195
7	12,816	15.654	15.654	1.899	0.378

TABLE III. THE SIZE OF DEFECT IS $25u \times 2$

Layout	Nets	$A_o(10^6)/u^2$	$A_{N}(10^{6})/u^{2}$	$T_o(10^4)/{ m s}$	$T_N(10^4)/{ m s}$
1	6577	17.236	17.236	0.950	0.259
2	4990	13.974	13.974	0.954	0.196
3	3696	5.552	5.552	0.464	0.097
4	30,824	99.013	99.013	5.744	1.656
5	23,505	69.848	69.848	5.208	1.211
6	6216	20.001	20.001	0.961	0.196
7	12,816	26.396	26.396	2.124	0.411

B. Implementation on Hadoop

Nowadays, IC scale becomes increasing larger, so it is not enough to only improve the efficiency of the model. Hadoop is a software framework allowing for the distributed processing of large amounts of data, whose characteristics are high reliability, efficiency, expansibility and high fault tolerance. So, we implement the model on Hadoop [24]. In order to test the efficiency of new model proposed in this paper, this model and the existing model in Reference [22] are implemented on the same Hadoop system. With Hadoop system built by three nodes, the configuration information and IP address of each node in the cluster are shown in Table IV. In addition, the operating system of each node is same, which is equipped with CentOS 6.3.

TABLE IV. THE SIZE OF DEFECT IS 18u×18u

configure	Master. Hadoop	Slave1.Hadoop	Slave2.Hadoop
IP			
address	192.168.1.219	192.168.1.220	192.168.1.221
		Pentium(R)	Pentium(R)
CPU	Pentium(R) D	Dual-CoreCPU	Dual-CoreCPU
	CPU 2.80GHz	E5800 @	E5800@
		3.20GHz	3.20GHz
Physical			
memory	2G	2G	2G
Hadoop			
version	Hadoop1.2.1	Hadoop1.2.1	Hadoop1.2.1

TABLE V. THE SIZE OF DEFECT IS $18u \times 18u$

Layout	$T_{OH}(10^4)/{ m s}$	$T_{NH}(10^4)/{ m s}$
1	0.282	0.074
2	0.216	0.047
3	0.119	0.029
4	1.545	0.247
5	1.127	0.182
6	0.258	0.056
7	0.551	0.112

TABLE VI.	THE SIZE OF DEFECT IS $20u \times 20u$
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Layout	$T_{OH}(10^4)/{ m s}$	$T_{\rm NH}(10^4)/{\rm s}$
1	0.283	0.077
2	0.244	0.049
3	0.137	0.029
4	1.592	0.363
5	1.140	0.274
6	0.269	0.058
7	0.569	0.113

TABLE VII.	THE SIZE OF DEFECT IS	$25u \times 25u$
	THE OLDE OF DEFECT ID	2500 ~ 2500

Layout	$T_{OH}(10^4)/{ m s}$	$T_{NH}(10^4)/{ m s}$
1	0.290	0.078
2	0.272	0.058
3	0.138	0.030
4	1.685	0.452
5	1.483	0.355
6	0.281	0.059
7	0.626	0.120

Experiment results is shown as Table V, Table VI and Table VII. With Hadoop, the column T_{OH} represents the extraction time applying the existing model in Reference [22], and T_{NH} represents the extraction time applying proposed model in this paper.

From Table V, Table VI and Table VII, T_{NH} is obviously less than T_{OH} , which verifies that the proposed model is also feasible for Hadoop. Moreover, the extraction efficiency of OCA is further improved.

IV. CONCLUSION

In this paper, a new model of OCA is proposed. It can improve the extraction efficiency of OCA. Furthermore, implemented on Hadoop, the novel model further raises the OCA extraction speed. On the real layout, the experimental results verify the high efficiency and accuracy of new model. The new model proposed in this paper can be widely used in IC because of its advantages. Moreover, this model can offer the valuable advice for layout optimization and yield evaluation, and then the cost of IC fabrication can be reduced.

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